



Welcome to **E-XFL.COM**

Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Obsolete
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	700MHz
Primary Attributes	FPGA - 350K Logic Elements
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA, FC (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5asxfb3g6f35c6n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Advantage	Supporting Feature
Lowest system cost	 Requires as few as four power supplies to operate Available in thermal composite flip chip ball-grid array (BGA) packaging Includes innovative features such as Configuration via Protocol (CvP), partial reconfiguration, and design security

Summary of Arria V Features

Table 2: Summary of Features for Arria V Devices

Feature	Description
Technology	 TSMC's 28-nm process technology: Arria V GX, GT, SX, and ST—28-nm low power (28LP) process Arria V GZ—28-nm high performance (28HP) process Lowest static power in its class (less than 1.2 W for 500K logic elements (LEs) at 85°C junction under typical conditions) 0.85 V, 1.1 V, or 1.15 V core nominal voltage
Packaging	 Thermal composite flip chip BGA packaging Multiple device densities with identical package footprints for seamless migration between different device densities Leaded⁽¹⁾, lead-free (Pb-free), and RoHS-compliant options
High-performance FPGA fabric	 Enhanced 8-input ALM with four registers Improved routing architecture to reduce congestion and improve compilation time
Internal memory blocks	 M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC) (Arria V GX, GT, SX, and ST devices only) M20K—20-Kb memory blocks with hard ECC (Arria V GZ devices only) Memory logic array block (MLAB)-640-bit distributed LUTRAM where you can use up to 50% of the ALMs as MLAB memory

Send Feedback

 $^{^{(1)}}$ Contact Altera for availability.

Resource		Member Code							
nesc	Juice	A1	А3	A 5	A7	B1	В3	B5	В7
6 Gbps Transceiver		9	9	24	24	24	24	36	36
GPIO ⁽³⁾		416	416	544	544	704	704	704	704
LVD S	Transmi tter	67	67	120	120	160	160	160	160
3	Receiver	80	80	136	136	176	176	176	176
PCIe I Block	PCIe Hard IP Block		1	2	2	2	2	2	2
Hard Memory Controller		2	2	4	4	4	4	4	4

Related Information

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 5: Package Plan for Arria V GX Devices

Member Code	F672 (27 mm)				F1152 (35 mm)		F1517 (40 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
A1	336	9	416	9	_	_	_	_
A3	336	9	416	9	_	_	_	_
A5	336	9	384	18	544	24	_	_
A7	336	9	384	18	544	24	_	_
B1	_	_	384	18	544	24	704	24
В3	_	_	384	18	544	24	704	24
B5	_	_	_	_	544	24	704	36
В7	_	_	_	_	544	24	704	36

Arria V GT

This section provides the available options, maximum resource counts, and package plan for the Arria V GT devices.



⁽³⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus[®] Prime software, the number of user I/Os includes transceiver I/Os.

Available Options

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

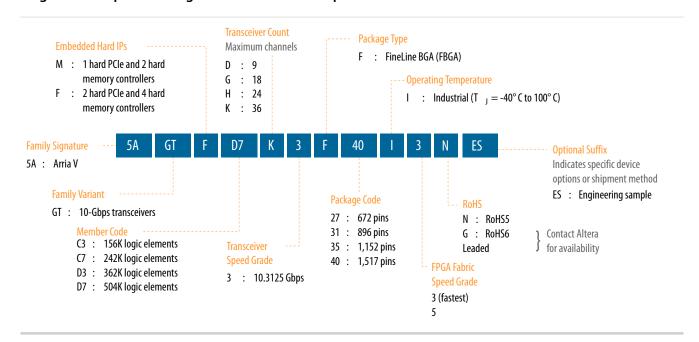
Related Information

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 2: Sample Ordering Code and Available Options for Arria V GT Devices



Maximum Resources

Table 6: Maximum Resource Counts for Arria V GT Devices

Resource		Member Code						
nes	nesource		C 7	D3	D7			
Logic Eleme	nts (LE) (K)	156	242	362	504			
ALM	ALM		91,680	136,880	190,240			
Register	Register		366,720	547,520	760,960			
Memory	M10K	10,510	13,660	17,260	24,140			
(Kb)	MLAB	961	1,448	2,098	2,906			
Variable-pre	Variable-precision DSP Block		800	1,045	1,156			
18 x 18 Mult	18 x 18 Multiplier		1,600	2,090	2,312			
PLL		10	12	12	16			



AV-51001 2015.12.21

and eighteen 10-Gbps, twelve 6-Gbps and sixteen 10-Gbps, fifteen 6-Gbps and fourteen 10-Gbps, or up to thirty-six 6-Gbps with no 10-Gbps channels.

Arria V GZ

This section provides the available options, maximum resource counts, and package plan for the Arria V GZ devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

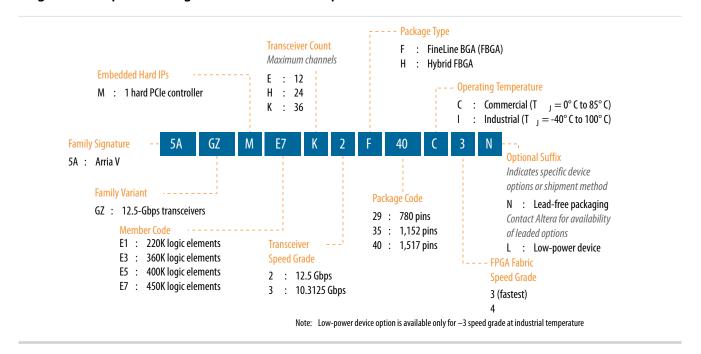
Related Information

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 3: Sample Ordering Code and Available Options for Arria V GZ Devices



Maximum Resources

Table 8: Maximum Resource Counts for Arria V GZ Devices

Resource	Member Code						
nesource	E1	E 3	E 5	E 7			
Logic Elements (LE) (K)	220	360	400	450			
ALM	83,020	135,840	150,960	169,800			
Register	332,080	543,360	603,840	679,200			



Pose	Resource -		Member Code						
nesc			E 3	E 5	E 7				
Memory	M20K	11,700	19,140	28,800	34,000				
(Kb)	MLAB	2,594	4,245	4,718	5,306				
Variable-pred	Variable-precision DSP Block		1,044	1,092	1,139				
18 x 18 Multi	18 x 18 Multiplier		2,088	2,184	2,278				
PLL	PLL		20	24	24				
12.5 Gbps Tr	ansceiver	24	24	36	36				
GPIO ⁽⁷⁾		414	414	674	674				
LVDS	Transmitter	99	99	166	166				
LVDS	Receiver	108	108	168	168				
PCIe Hard IF	Block	1	1	1	1				

Related Information

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 9: Package Plan for Arria V GZ Devices

Member Code	H780 (33 mm)			152 mm)	F1517 (40 mm)		
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	
E1	342	12	414	24	_	_	
E3	342	12	414	24	_	_	
E5	_	_	534	24	674	36	
E7	_	_	534	24	674	36	

Arria V SX

This section provides the available options, maximum resource counts, and package plan for the Arria V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.



⁽⁷⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

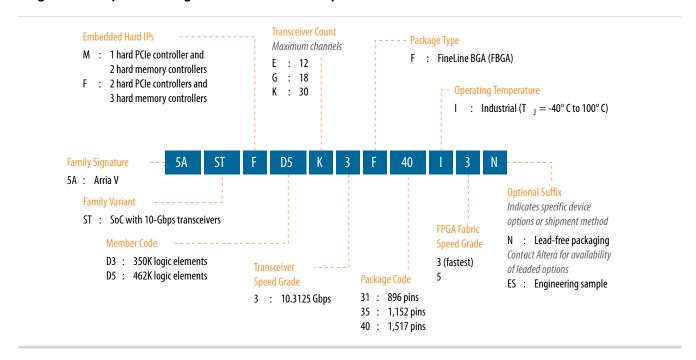
Related Information

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 5: Sample Ordering Code and Available Options for Arria V ST Devices



Maximum Resources

Table 12: Maximum Resource Counts for Arria V ST Devices

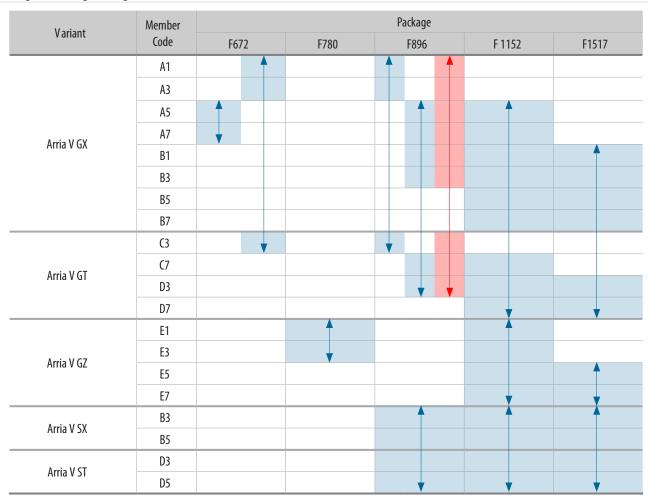
Reso	LINEO	Member Code			
Reso	ource	D3	D5		
Logic Elements (LE)	(K)	350	462		
ALM		132,075	174,340		
Register		528,300	697,360		
Memory (Kb)	M10K	17,290	22,820		
Memory (Rb)	MLAB	2,014	2,658		
Variable-precision D	SP Block	809	1,090		
18 x 18 Multiplier		1,618	2,180		
FPGA PLL		14	14		
HPS PLL		3	3		
Transceiver	6-Gbps	30	30		
Transcerver	10-Gbps ⁽⁹⁾	16	16		



I/O Vertical Migration for Arria V Devices

Figure 6: Vertical Migration Capability Across Arria V Device Packages and Densities

The arrows indicate the vertical migration paths. Some packages have several migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 320 GPIOs, up to nine 6 Gbps transceiver channels, and up to four 10 Gbps transceiver (for Arria V GT devices). This migration path is not shown in the Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the Pin Migration View window in the Quartus Prime software Pin Planner.

Note: Except for Arria V GX A5 and A7, and Arria V GT C7 devices, all other Arria V GX and GT devices require a specific power-up sequence. If you plan to migrate your design from Arria V GX A5 and A7, and Arria V GT C7 devices to other Arria V devices, your design must adhere to the same required power-up sequence.



Table 15: Number of Multipliers in Arria V Devices

The table lists the variable-precision DSP resources by bit precision for each Arria V device.

Variant	Mem ber	Variable- precision	Independ				Multiplier Adder Summ			
ranant	Code	DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	36 x 36 Multiplier	Adder Mode	with 36 bit Input		
	A1	240	720	480	240	_	240	240		
	A3	396	1,188	792	396	_	396	396		
	A5	600	1,800	1,200	600	_	600	600		
Arria V	A7	800	2,400	1,600	800	_	800	800		
GX	B1	920	2,760	1,840	920	_	920	920		
	В3	1,045	3,135	2,090	1,045	_	1,045	1,045		
	B5	1,092	3,276	2,184	1,092	_	1,092	1,092		
	B7	1,156	3,468	2,312	1,156	_	1,156	1,156		
	C3	396	1,188	792	396	_	396	396		
Arria V	C7	800	2,400	1,600	800	_	800	800		
GT	D3	1,045	3,135	2,090	1,045	_	1,045	1,045		
	D7	1,156	3,468	2,312	1,156	_	1,156	1,156		
	E1	800	2,400	1,600	800	400	800	800		
Arria V	E3	1,044	3,132	2,088	1,044	522	1,044	1,044		
GZ	E5	1,092	3,276	2,184	1,092	546	1,092	1,092		
	E7	1,139	3,417	2,278	1,139	569	1,139	1,139		
Arria V	В3	809	2,427	1,618	809	_	809	809		
SX	B5	1,090	3,270	2,180	1,090	_	1,090	1,090		
Arria V	D3	809	2,427	1,618	809	_	809	809		
ST	D5	1,090	3,270	2,180	1,090	_	1,090	1,090		

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



		M20K		M1	ОК	MLAB		
Variant	Membe r Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)
Arrio V ST	D3	_	_	1,729	17,290	3223	2,014	19,304
Arria V ST	D5	_	_	2,282	22,820	4253	2,658	25,478

Embedded Memory Configurations

Table 17: Supported Embedded Memory Block Configurations for Arria V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MIAD	32	x16, x18, or x20
MLAB	64 ⁽¹¹⁾	x10
	512	x40
	1K	x20
M20K	2K	x10
WIZOK	4K	x5
	8K	x2
	16K	x1
	256	x40 or x32
	512	x20 or x16
M10K	1K	x10 or x8
	2K	x5 or x4
	4K	x2
	8K	x1

Clock Networks and PLL Clock Sources

650 MHz Arria V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Altera's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

Note: To reduce power consumption, the Quartus Prime software identifies all unused sections of the clock network and powers them down.



⁽¹¹⁾ Available for Arria V GZ devices only.

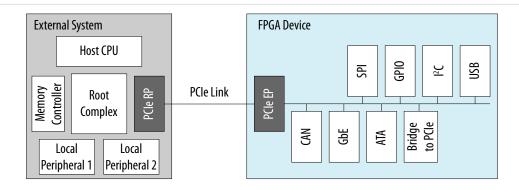
PCIe Gen1, Gen2, and Gen 3 Hard IP

Arria V devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen3, Gen 2, and Gen 1 end point and root port for up to x8 lane configuration.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 8: PCIe Multifunction for Arria V Devices



The Arria V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Arria V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Arria V device provides improved end-to-end datapath protection using ECC.

External Memory Interface

This section provides an overview of the external memory interface in Arria V devices.

Hard and Soft Memory Controllers

Arria V GX,GT, SX, and ST devices support up to four hard memory controllers for DDR3 and DDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Arria V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Arria V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices, QDR II+, QDR II, and DDR II+ SRAM devices, and RLDRAM II devices for maximum flexibility.

Note: DDR3 SDRAM leveling is supported only in Arria V GZ devices.



24

External Memory Performance

Table 18: External Memory Interface Performance in Arria V Devices

Interface	Voltage	Hard Controller (MHz)	Soft Controller (MHz)		
interrace	(V)	Arria V GX, GT, SX, and ST	Arria V GX, GT, SX, and ST	Arria V GZ	
DDR3 SDRAM	1.5	533	667	800	
DDR3 3DRAM	1.35	533	600	800	
DDR2 SDRAM	1.8	400	400	400	
LPDDR2 SDRAM	1.2	_	400	_	
RLDRAM 3	1.2	_	_	667	
RLDRAM II	1.8	_	400	533	
	1.5	_	400	533	
QDR II+ SRAM	1.8	_	400	500	
	1.5	_	400	500	
QDR II SRAM	1.8	_	400	333	
QDK II SKAWI	1.5	_	400	333	
DDR II+	1.8	_	400	_	
SRAM ⁽¹²⁾	1.5	_	400	_	

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 19: HPS External Memory Interface Performance

The hard processor system (HPS) is available in Arria V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	533
DDR3 3DRAM	1.35	533
LPDDR2 SDRAM	1.2	333



⁽¹²⁾ Not available as Altera® IP.

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Arria V devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at less than 170 mW
- 10 Gbps transceivers at less than 165 mW
- 6 Gbps transceivers at less than 105 mW

Arria V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left and right outer edges of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

The following figures are graphical representations of a top view of the silicon die, which corresponds to a reverse view for flip chip packages. Different Arria V devices may have different floorplans than the ones shown in the figures.



Figure 9: Device Chip Overview for Arria V GX and GT Devices

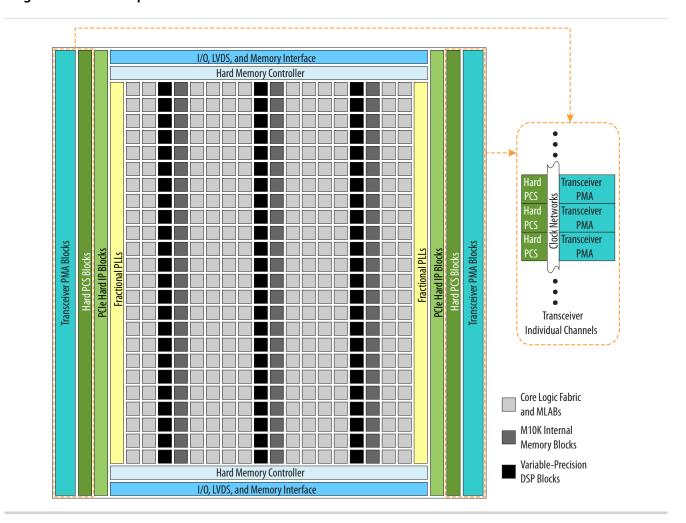




Figure 10: Device Chip Overview for Arria V GZ Devices

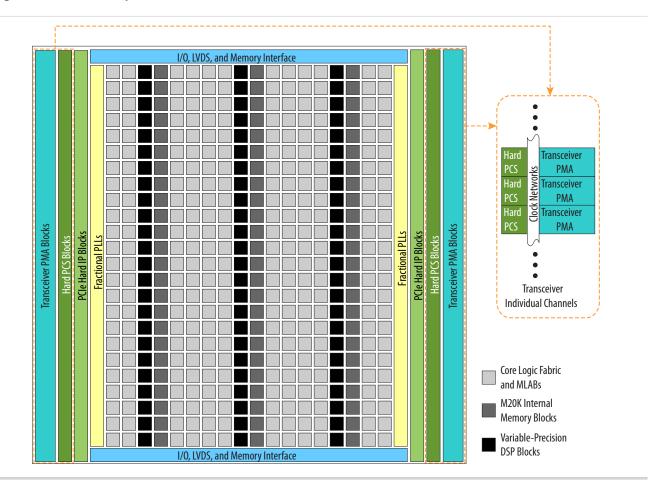




Table 22: Transceiver PCS Features for Arria V GZ Devices

Protocol	Data Rates (Gbps)	Transmitter Data Path Features	Receiver Data Path Features
Custom PHY GPON	0.6 to 9.80 1.25 and 2.5	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering
Custom 10G PHY	9.98 to 12.5	TX FIFOGear boxBit-slip	RX FIFOGear box
PCIe Gen1 (x1, x2 x4, x8) PCIe Gen2 (x1, x2, x4, x8)	2.5 and 5.0	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding PIPE 2.0 interface to core logic 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer, Byte ordering PIPE 2.0 interface to core logic
PCIe Gen3 (x1, x2, x4, x8)	8.0	 Phase compensation FIFO 128B/130B encoder Scrambler Gear box Bit-slip 	 Block synchronization Rate match FIFO 128B/130B decoder Descrambler Phase compensation FIFO
10GbE	10.3125	TX FIFO64B/66B encoderScramblerGear box	 RX FIFO 64B/66B decoder Descrambler Block synchronization Gear box
Interlaken	3.125 to 12.5	 TX FIFO Frame generator CRC-32 generator Scrambler Disparity generator Gear box 	 RX FIFO Frame generator CRC-32 checker Frame decoder Descrambler Disparity checker Block synchronization Gear box



Protocol	Data Rates (Gbps)	Transmitter Data Path Features	Receiver Data Path Features
40GBASE-R Ethernet 100GBASE-R Ethernet	4 x 10.3125 10 x 10.3125	 TX FIFO 64B/66B encoder Scrambler Alignment marker insertion Gearbox Block stripper 	 RX FIFO 64B/66B decoder Descrambler Lane reorder Deskew Alignment marker lock Block synchronization Gear box Destripper
40G and 100G OTN	(4+1) x 11.3 (10+1) x 11.3	 TX FIFO Channel bonding Byte serializer	RX FIFOLane deskewByte deserializer
GbE	1.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding GbE state machine 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering GbE state machine
XAUI	3.125 to 4.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding XAUI state machine for bonding four channels 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering XAUI state machine for realigning four channels
SRIO	1.25 to 6.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding SRIO V2.1-compliant x2 and x4 channel bonding 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering SRIO V2.1-compliant x2 and x4 deskew state machine



Mode	Data Width	Max Clock Rate (MHz)	Max Data I Rate (Mbps)	Decompression	Design Security F	Partial econfiguratio (20)	Remote System Update
	8 bits	125	_	Yes	Yes	_	
FPP	16 bits	125	_	Yes	Yes	Yes ⁽²¹⁾	Parallel flash loader
	32 bits ⁽²²⁾	100	_	Yes	Yes	_	
CvP (PCIe)	x1, x2, x4, and x8 lanes	_	_	Yes	Yes	Yes	_
JTAG	1 bit	33	33	_	_	_	_
Configuration	16 bits	125	_	Yes	Yes	Yes (21)	Parallel flash loader
via HPS	32 bits	100	_	Yes	Yes	_	rafanei nasn loadei

Instead of using an external flash or ROM, you can configure the Arria V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Arria V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Note: Although Arria V GZ devices support PCIe Gen3, you can use only PCIe Gen1 and PCIe Gen2 for CvP configuration scheme.

Related Information

Configuration via Protocol (CvP) Implementation in Altera FPGAs User Guide Provides more information about CvP.

Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Arria V devices consume less power than previous generation Arria V FPGAs:

- Total device core power consumption—less by up to 50%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Arria V devices contain several hard IP blocks, including PCIe Gen1, Gen2, and Gen3, GbE, SRIO, GPON, and CPRI protocols, that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.



⁽²⁰⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

⁽²¹⁾ Supported at a maximum clock rate of 62.5 MHz.

⁽²²⁾ Arria V GZ only

Document Revision History

Date	Version	Changes
December 2015	2015.12.21	 Updated RoHS and optional suffix information in sample ordering code and available options diagrams for Arria V GX and GT devices. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
January 2015	2015.01.23	 Updated package dimension for Arria V GZ H780 package from 29 mm to 33 mm. Updated dual-core ARM Cortex-A9 MPCore processor maximum frequency from 800 MHz to 1.05 GHz.
December 2013	2013.12.26	 10-Gbps Ethernet (10GbE) PCS and Interlaken PCS are for Arria V GZ only. Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. Added link to Altera Product Selector for each device variant. Added leaded package options. Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F896 package from 170 to 250. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1152 package from 350 to 385. Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1517 package from 528 to 540. Corrected LVDS Transmitter for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 devices from 121 to 120. Added links to Altera's External Memory Spec Estimator tool to the topics listing the external memory interface performance. Added x2 for PCIe Gen3, Gen 2, and Gen 1.
August 2013	2013.08.19	 Removed the note about the PCIe hard IP on the right side of the device in the F896 package of the Arria V GX variant. These devices do not have PCIe hard IP on the right side. Added transceiver speed grade 6 to the available options of the Arria V SX variant. Corrected the maximum LVDS transmitter channel counts for the Arria V GX A1 and A3 devices from 68 to 67. Corrected the maximum FPGA GPIO count for Arria V ST D5 devices from 540 to 528.



Date	Version	Changes
June 2013	2013.06.03	Removed statements about contacting Altera for SFF-8431 compliance requirements. Refer to the Transceiver Architecture in Arria V Devices chapter for the requirements.
May 2013	2013.05.06	 Moved all links to the Related Information section of respective topics for easy reference. Added link to the known document issues in the Knowledge Base. Updated the available options, maximum resource counts, and per package information for the Arria V SX and ST device variants. Updated the variable DSP multipliers counts for the Arria V SX and ST device variants. Clarified that partial reconfiguration is an advanced feature. Contact Altera for support of the feature. Added footnote to clarify that MLAB 64 bits depth is available only for Arria V GZ devices. Updated description about power-up sequence requirement for device migration to improve clarity.
January 2013	2013.01.11	 Added the L optional suffix to the Arria V GZ ordering code for the – I3 speed grade. Added a note about the power-up sequence requirement if you plan to migrate your design from the Arria V GX A5 and A7, and Arria V GT C7 devices to other Arria V devices.
November 2012	2012.11.19	 Updated the summary of features. Updated Arria V GZ information regarding 3.3 V I/O support. Removed Arria V GZ engineering sample ordering code. Updated the maximum resource counts for Arria V GX and GZ. Updated Arria V ST ordering codes for transceiver count. Updated transceiver counts for Arria V ST packages. Added simplified floorplan diagrams for Arria V GZ, SX, and ST. Added FPP x32 configuration mode for Arria V GZ only. Updated CvP (PCIe) remote system update support information. Added HPS external memory performance information. Updated template.
October 2012	3.0	 Added Arria V GZ information. Updated Table 1, Table 2, Table 3, Table 14, Table 15, Table 16, Table 17, Table 18, Table 19, Table 20, and Table 21. Added the "Arria V GZ" section. Added Table 8, Table 9 and Table 22.



Date	Version	Changes
July 2012	2.1	 Added –I3 speed grade to Figure 1 for Arria V GX devices. Updated the 6-Gbps transceiver speed from 6.553 Gbps to 6.5536 Gbps in Figure 3 and Figure 1.
June 2012	2.0	 Restructured the document. Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections. Added Table 1, Table 3, Table 12, Table 15, and Table 16. Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 13, Table 14, and Table 19. Updated Figure 1, Figure 2, Figure 3, Figure 4, and Figure 8. Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. Text edits throughout the document.
February 2012	1.3	 Updated Table 1–7 and Table 1–8. Updated Figure 1–9 and Figure 1–10. Minor text edits.
December 2011	1.2	Minor text edits.
November 2011	1.1	 Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–6, Table 1–7, Table 1–9, and Table 1–10. Added "SoC FPGA with HPS" section. Updated "Clock Networks and PLL Clock Sources" and "Ordering Information" sections. Updated Figure 1–5. Added Figure 1–6. Minor text edits.
August 2011	1.0	Initial release.

